IPC ASSOCIATION CONN ELECTRONICS INDU	Material Compo © Copyright 2005. IP international and Pan-	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				Materials and	ials and Mfg Information			
upplier Inf	formation													
Company name* Company unique ID			ique ID	Unique I		Unique ID Auth	ique ID Authority			Response Date*				
nsemi											2023-06-08			
Contact Name Tit				Title - Contact			Phone - Contact*				Email - Contact*			
Product-Env-Stewards Product				oduct Enviro Compliance			NA			Produ	Product-Env-Stewards@onsemi.com			
Authorized Representative* Title - Rep				epresentative			Phone - Representative*			Email	Email - Representative*			
Product-Env-Stewards Product Envir				iro Compliance			NA			Produ	Product-Env-Stewards@onsemi.com			
Req	quester Item Number	Mfr Item		Mfr Item Name			Effective Date	Version	Manufacturing Si	te	Weight*	UOM	Unit Type	
		AP13020 A0-DR1	CSSL00SMG	13 MP Co-Proces	ssor		2023-06-08		MY5		68.1	mg	Each	
lanufactur	ring Proccess Informat	tion												
Tern	Terminal Plating / Grid Array Material		Геrminal Base Alloy J-STD-020 MS		L Rating	Peak Process Body Temperature Max Time at Pe		Peak Temper	rature Numb	er of Reflow Cy	cles			
SnA	SnAgCu		CU Alloy 4		4		260	С	30	seco	onds 3			

RoHS Material Composition Declaration			Declaration Type *	Detail	ed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		ium (Cr6+), Polybrominated Biphenyls (PB)	erial for Cadmium and quantity limit of 0.1% b B), Polybrominated Diphenyl Ethers (PBDE), a		
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct tion member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted
Exemption: If the declared item does not applicable exemptions.	contain RoHS restricted substances per t	he definition above except for defined Rol	IS exemptions, then select the corresponding	response in the R	oHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	8.02	mg	Supplier	Silicon (Si)	7440-21-3		7.9903	mg
			Supplier	Polyimide	Proprietary Data		0.0297	mg
Die Attach	0.8	mg	Supplier	Epoxy resins	129915-35-1		0.06	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		0.436	mg
			Supplier	Acrylic resins	Proprietary Data		0.084	mg
			Supplier	Polyimide	Proprietary Data		0.22	mg
Mold Compound-Black	33.8	mg		Phenolic Resin	proprietary data		1.521	mg
			Supplier	Epoxy Phenol Resin	Proprietary Data		2.028	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1014	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		1.014	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		25.6542	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		3.4814	mg
Solder Ball	12.56	mg	Supplier	Silver (Ag)	7440-22-4		0.3768	mg
			Supplier	Tin (Sn)	7440-31-5		12.1204	mg
			Supplier	Copper (Cu)	7440-50-8		0.0628	mg
Substrate and Solder Mask	12.31	mg	Supplier	Fiber Glass (SiO2)	65997-17-3		2.6085	mg
			В	Nickel (Ni)	7440-02-0		0.2339	mg
			Supplier	Gold (Au)	7440-57-5		0.0308	mg
			Supplier	Cured Resin of Solder Mask	Proprietary Data		1.7505	mg
			Supplier	Bismaleimide Triazine resin	Proprietary Data		1.6101	mg
			Supplier	Copper (Cu)	7440-50-8		6.0762	mg
Wire Bond - Au	0.61	mg	Supplier	Gold (Au)	7440-57-5		0.61	mg